

# 承 认 书

## SPECIFICATION FOR APPROVAL

产品型号 (MODEL NO) : **EM-6013P**

指 向 性 (DIRECTINITY) : 全指向性 (Omni-directional)

CUSTOMER	接收 Prepared	复核 Checked	批准 Approved
JIUSHENG	编制 Prepared	复核 Checked	批准 Approved

### SPECIFICATION HISTORY

规格确认历程

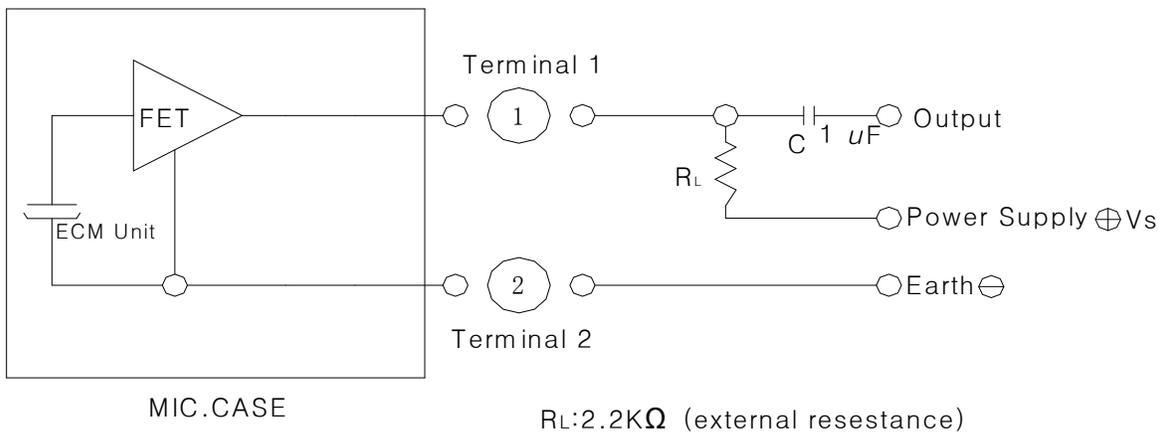
History Change 更改记录	Date 日期	Item 项目	Contents 内容	Grounds 范围
ISSUE 确认  From 开始  To 到	2012 .03 .25			
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1. SCOPE 范围	This specification shall be applied to electret condenser microphone(ECM) 本规格说明书适用于驻极体传声器						
2. MODEL NO. 产品型号	EM-6013P						
3 ELECTRICAL CHARACTERISTICS 电气特性							
Temp. 环境温度	20 ± 2°C						
Room Humidity 相对湿度	65 ± 5%						
NO. 序号	Parameter 参数	Symbol 符号	Condition 测试条件	Limits 范围			Unit (单位)
				Min. 最小值	Center 中心值	Max. 最大值	
1	Sensitivity 灵敏度	S	f=1kHz, S.P.L=1Pa, 0dB=1V/Pa	-47	-44	-41	dB
2	Output impedance 输出阻抗	Z <sub>OUT</sub>	f= 1kHz			2.2	KΩ
3	Current Consumption 消耗电流	I <sub>DDs</sub>	V <sub>CC</sub> =2.0V , R <sub>L</sub> =2.2KΩ	150		500	μA
4	Signal to Noise Ratio 信噪比	S/N	f=1 kHz , S.P.L=1Pa	60			dB
5	Decreasing Voltage 减电压灵敏度	ΔS-VS	V <sub>CC</sub> =2.0V to 1.5V			-3	dB
6	Operating Voltage 工作电压			1		10	V
7	Maximum input S.P.L 最大输入声压					110	dB

#### 4. MEASUREMENT CIRCUIT 测试电路



5. TYPICAL FREQUENCY RESPONSE CURVE (FAR FIELD) 频响曲线

Far Field Measurement Condition 自由场测试条件

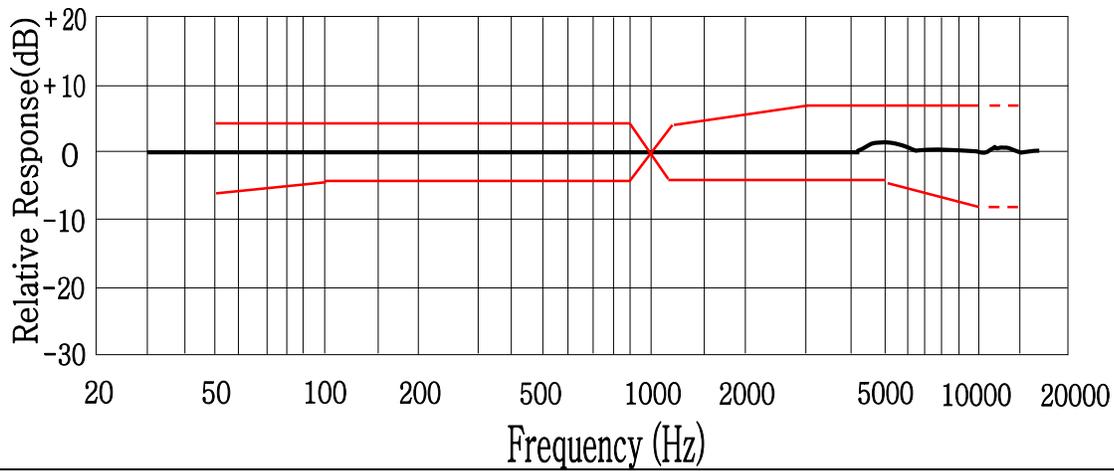
Temperature 温度 : 20 ± 2 °C

Bias Voltage 基准电压: 2.0V (with 2.2KΩ series resistor 2.2KΩ 电阻)

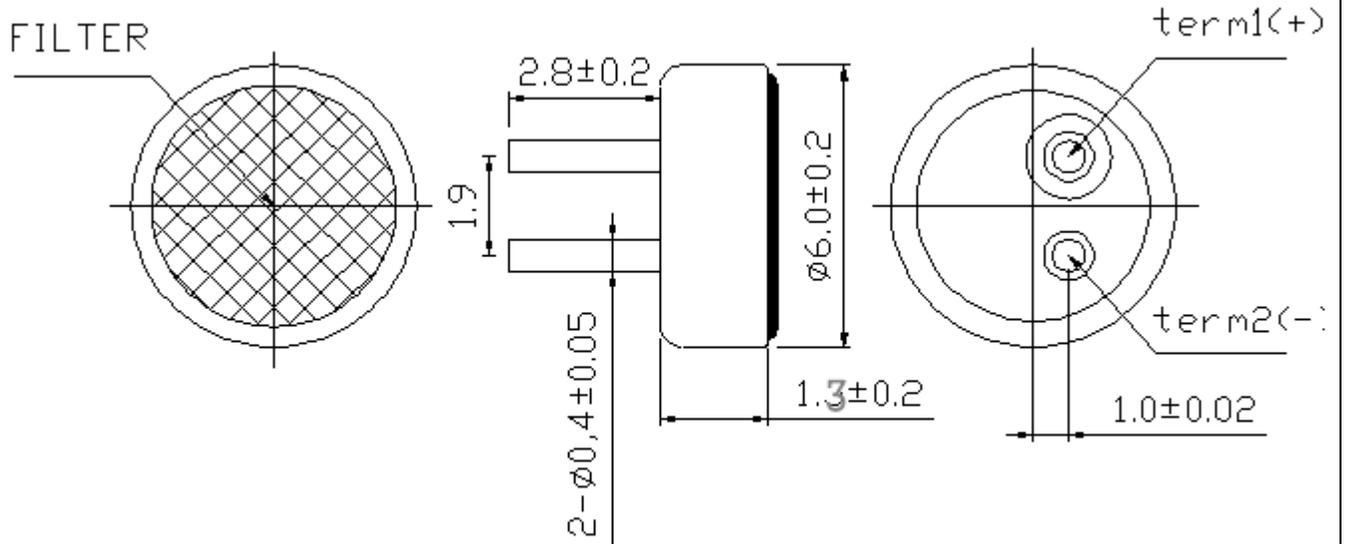
Acoustic stimulus :1Pa (94Db SPL at 1 **KHZ**) at 50cm from the loud-speaker.

声音条件: The loud-speaker must be calibrated to make a flat frequency response input signal  
距离扬声器 50cm 出产生 1Pa 声压。 扬声器必须先用标准输入信号事先校准。

Position: The frequency response of microphone unit measured at 50cm from the loud-speaker  
位置 : 扬声器距离待测话筒 50cm.

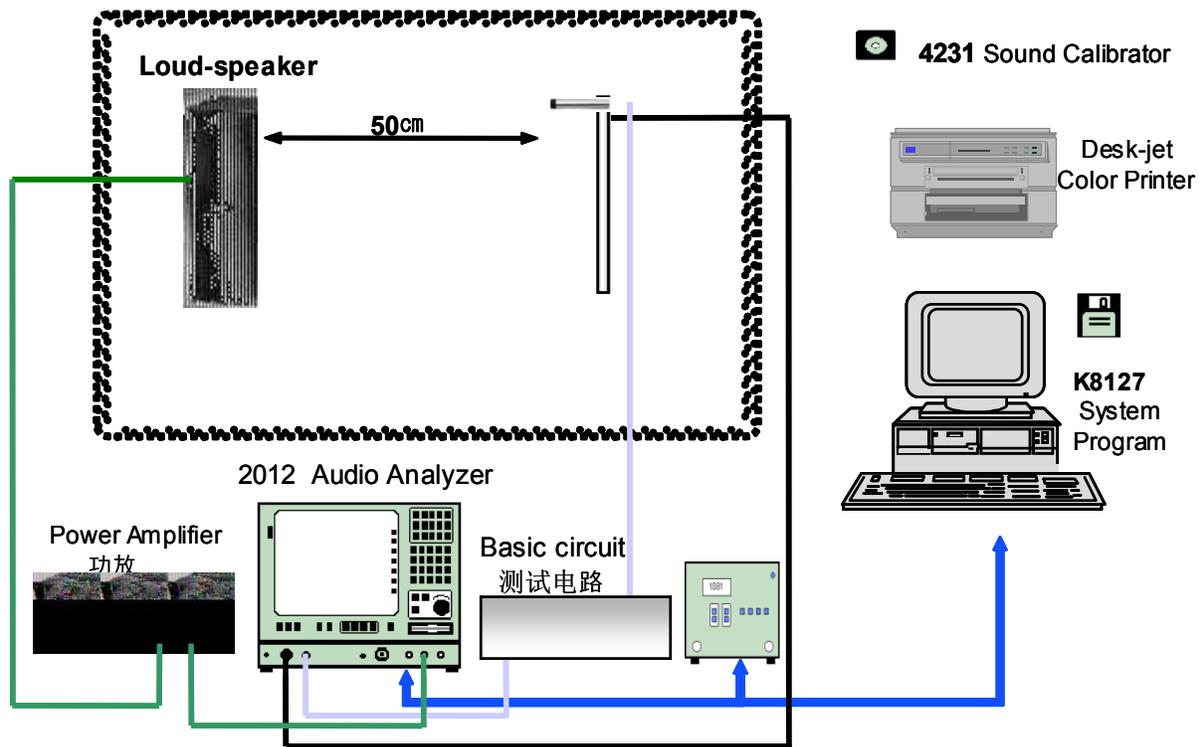


6. DIMENSIONAL DRAWING 外形图





## 9. MEASUREMENT SYSTEM 测量系统



## 10. REGARDING THE SOLDERING OPERATION 焊接注意事项

Every ECM contains a FET with microphone body. This FET is easy to be damaged from excessive heat and electrical shock. Proper attention for the soldering work is required same as followings.

每个 ECM 都包含有个 FET. FET 在过热和电流冲击下容易损坏。应遵循以下焊接操作规程：

1 -Recommend to use 15W ~ 17W ceramic soldering iron and apply  $270 \pm 10^\circ\text{C}$  temperature range

推荐使用功率在 15W-17W，温度变化范围在  $270 \pm 10^\circ\text{C}$  的陶瓷电烙铁。

2 -Soldering should be accomplished within 2 seconds at each terminal so as not to be overheated.

为防止过热，焊接应在 2 秒内完成。

3 -ECM shall be soldered fixed on the metal block (heat sink) which has the higher radiation effects. Heat sink shall contact with each of ECM.

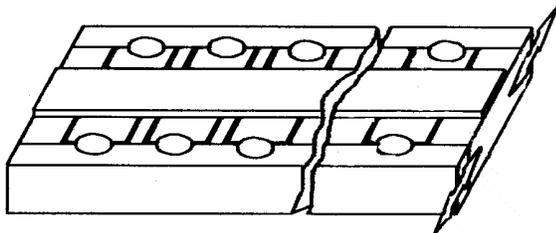
应把驻极体传声器固定在散热良好的金属装置（散热板）上进行焊接。

4 -The pin hole soldering shall be avoided.

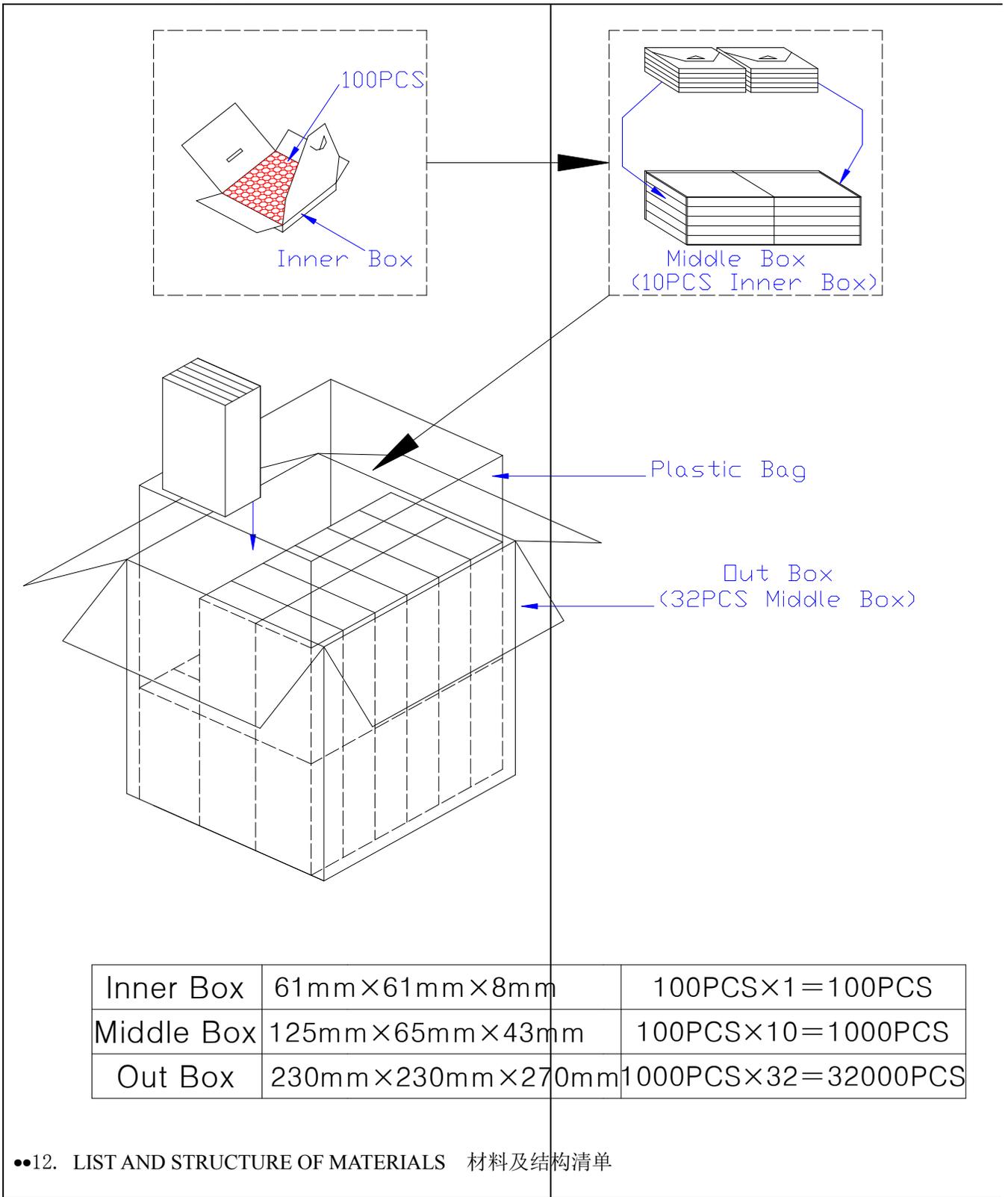
焊接后，各焊点不应出现砂眼（焊锡小孔）现象。

5 -E.C.M may easily destroyed by the static electricity, and the countermeasure for eliminating the static electricity (the ground for soldering copper, for worktable and for human body) shall be executed.

驻极体传声器容易受静电破坏，应采取防静电措施（焊接器具，工作台，操作人员人体应接地）

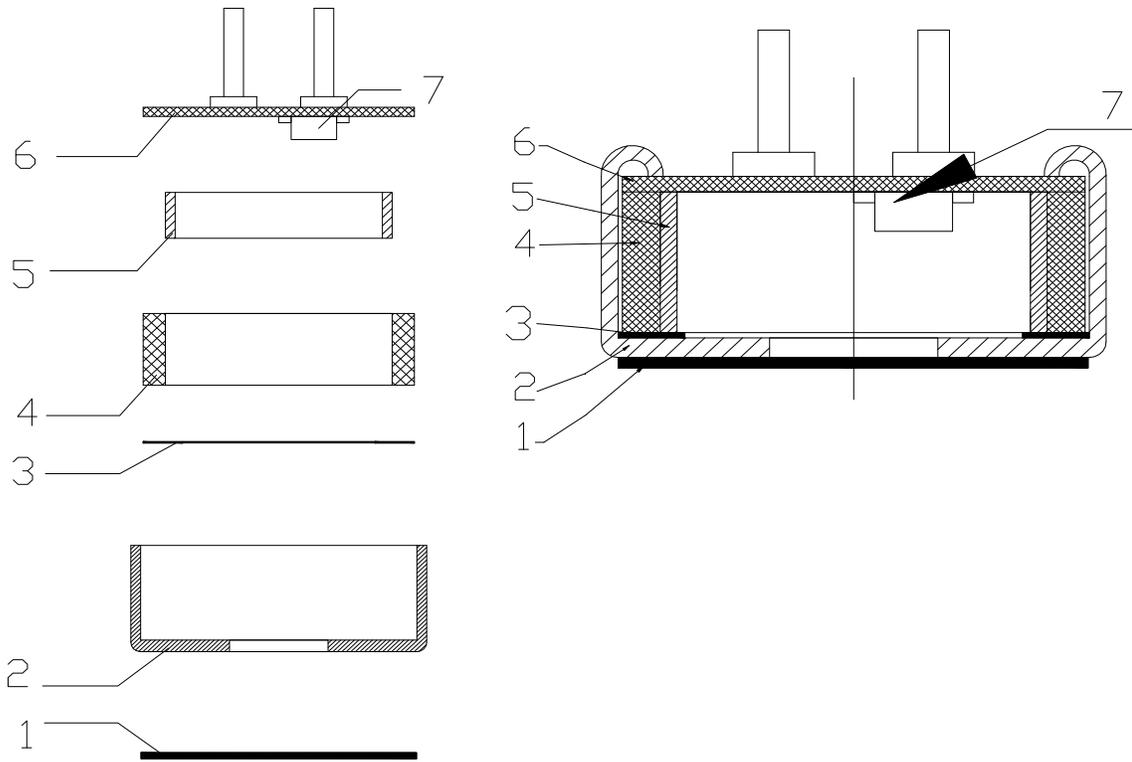


11. PACKAGE 包装图



••12. LIST AND STRUCTURE OF MATERIALS 材料及结构清单

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No. 序号	Part name	部件名称
1	防水网	FELT
2	外壳	Case
3	垫片	Spacer
4	塑环	Housing Chamber
5	振膜	Diaphragm
6	线路板	P.C.B
7	管芯	FET